ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composit © Copyright 2005. IPC, I international and Pan-An	Bannockb	urn, Illinois. A	ll rights reserved untions.	under both	This docume level parts, t	ent is a declarat	ion of the sencompasse	substances es all low	s within the manuf er level materials f	acturer liste or which th	d item. Note: i e manufacturer	f the item is an as r has engineering	ssembly with lower responsibility.	
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					aterials and	als and Mfg Information				
Supplier Informa	tion														
Company name*			Company unique ID				Unique ID Authority					Response Date*			
onsemi											2023-	2023-06-08			
Contact Name			Title - Contact				Phone - Contact*				Emai	Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance				NA				Prod	Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative				Phone - Representative*				Emai	Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance				NA				Prod	Product-Env-Stewards@onsemi.com			
Requester	Requester Item Number Mfr Iten		n Number Mfr Item Name				Effective Date	Version	1	Manufacturing Sit	e	Weight*	UOM	Unit Type	
		LC87F5WC8AVU- QIP-H 8-bit Microcon		8-bit Microcontro	oller		2023-06-08					1500.0	mg	Each	
Manufacturing P	roccess Information	1													
Terminal Plating / Grid Array Material T		Ferminal Base Alloy J-STD-020		J-STD-020 MS	L Rating	Peak Process Body Temperat		are Max Time at I	Peak Tempe	erature Numb	per of Reflow Cy	cles			
contains Bi			CU Alloy 3			260 C 30		30	sec	seconds 3					
Comments															
ATTENTION: MSL 3	Rated item requires Ba	ke and D	ry Pack (after	electrical test)											
For more information	regarding material com	position	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	4.44	mg	Supplier	Silicon (Si)	7440-21-3		4.4125	mg
			Supplier	Polyimide	Proprietary Data		0.0275	mg
Die Attach	0.43	mg	Supplier	Silver (Ag)	7440-22-4		0.3289	mg
			Supplier	Epoxy resins	129915-35-1		0.1011	mg
Lead Frame	350.5	mg	Supplier	Silver (Ag)	7440-22-4		0.4907	mg
			Supplier	Tin (Sn)	7440-31-5		4.3462	mg
			Supplier	Zinc (Zn)	7440-66-6		1.0164	mg
			Supplier	Silicon (Si)	7440-21-3		2.4184	mg
			В	Nickel (Ni)	7440-02-0		11.181	mg
			Supplier	Copper (Cu)	7440-50-8		331.0472	mg
Mold Compound-Black	1132.09	mg		Epoxy Phenol Resin	proprietary data		135.8508	mg
			Supplier	Carbon Black (C)	1333-86-4		4.5284	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		957.748	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		33.9627	mg
Plating	10.65	mg	В	Bismuth (Bi)	7440-69-9		0.0639	mg
			Supplier	Tin (Sn)	7440-31-5		10.5861	mg
Wire Bond - Au	1.89	mg	Supplier	Gold (Au)	7440-57-5		1.89	mg